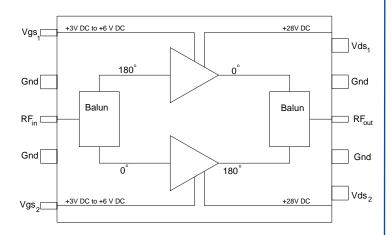


Product Description

Key Specifications

Sirenza Microdevices' **SDM-08060-B1F** 65W power module is a robust, impedance matched, single-stage, push-pull Class AB amplifier module suitable for use as a power amplifier driver or output stage. The power transistors are fabricated using Sirenza's latest, high performance LDMOS process. It is a drop-in, no-tune solution for high power applications requiring high efficiency, excellent linearity, and unit-to-unit repeatability. It is internally matched to 50 ohms.

Functional Block Diagram



Case Flange = Ground

SDM-08060-B1F SDM-08060-B1FY



869-894 MHz Class AB 65W Power Amplifier Module



Product Features

- Available in RoHS compliant packaging
- 50 Ω RF impedance
- 65W Output P_{1dB}
- Single Supply Operation : Nominally 28V
- High Gain: 17 dB at 880 MHz
- High Efficiency: 46% at 880 MHz
- ESD Protection: JEDEC Class 2 (2000V HBM)

Applications

- Base Station PA driver
- Repeater
- CDMA
- GSM / EDGE

Symbol	Parameter	Units	Min.	Тур.	Max.
Frequency	Frequency of Operation	MHz	869	-	894
P _{1dB}	Output Power at 1dB Compression, 881 MHz	W	60	65	-
Gain	Gain at 12W CDMA Output (Single Carrier IS-95), 881MHz	dB	16	17	-
Gain Flatness	Peak to Peak Gain Variation, 869 - 894MHz	dB	-	0.3	0.5
Efficiency	Drain Efficiency at 60W PEP, 880MHz and 881MHz	%	32	34	-
Efficiency	Drain Efficiency at 60W CW, 880MHz	%		46	-
IRL	Input Return Loss 12W CW Output Power, 869 - 894MHz	dB	-	-15	-10
IMD	3rd Order IMD Product, 60W PEP, 880MHz and 881MHz	dBc	-	-31	-28
Delay	Signal Delay from Pin 3 to Pin 8	nS	-	4.0	-
Phase Linearity	Deviation from Linear Phase (Peak to Peak)	Deg	-	0.5	-
R _{TH}	Thermal Resistance (Junction to Case)	°C/W		1.5	
***	n = Z _{out} = 50Ω, V _{DD} = 28.0V, I _{DQ1} = I _{DQ2} =300m <i>A</i> . T _{Flange} = 25°C	0,		0	

Quality Specifications

,			
Parameter	Description	Unit	Typical
ESD Rating	Human Body Model	Volts	2000
MTTF	200°C Channel	Hours	1.2 X 10 ⁶

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303 S. Technology Court,

Phone: (800) SMI-MMIC

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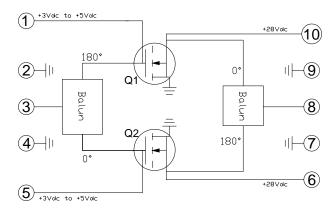
Broomfield CO 80021



Pin Description

Pin#	Function	Description	
1	V_{GS1}	LDMOS FET Q1 gate bias. V _{GSTH} 3.0 to 5.0 VDC. See Notes 2, 3 and 4	
2,4,7,9	Ground	Module Topside ground.	
3	RF Input	Internally DC blocked	
5	V_{GS2}	LDMOS FET Q2 gate bias. V _{GSTH} 3.0 to 5.0 VDC. See Notes 2, 3 and 4	
6	V_{D2}	LDMOS FET Q2 drain bias. See Note 1.	
8	RF Output	Internally DC blocked	
10	V_{D1}	LDMOS FET Q1 drain bias. See Note 1.	
Flange	Ground	Baseplate provides electrical ground and a thermal transfer path for the device. Proper mounting assures optimal performance and the highest reliability. See Sirenza applications note AN-054 Detailed Installation Instructions for Power Modules.	

Simplified Device Schematic



Case Flange = Ground

Absolute Maximum Ratings

Parameters	Value	Unit
Drain Voltage (V _{DD})	35	V
RF Input Power	+37	dBm
Load Impedance for Continuous Operation Without Damage	5:1	VSWR
Control (Gate) Voltage, VDD = 0 VDC	15	V
Output Device Channel Temperature	+200	°C
Operating Temperature Range	-20 to +90	°C
Storage Temperature Range	-40 to +100	°C

Operation of this device beyond any one of these limits may cause permanent damage. For reliable continuous operation see typical setup values specified in the table on page one.

Note 1:

Internal RF decoupling is included on all bias leads. No additional bypass elements are required, however some applications may require energy storage on the V_D leads to accommodate modulated signals.

Note 2:

Gate voltage must be applied to V_{GS} leads simultaneously with or after application of drain voltage to prevent potentially destructive oscillations. Bias voltages should never be applied to a module unless it is properly terminated on both input and output.

Note 3

The required V $_{GS}$ corresponding to a specific I $_{DQ}$ will vary from module to module and may differ between V $_{GS1}$ and V $_{GS2}$ on the same module by as much as ± 0.10 volts due to the normal die-to-die variation in threshold voltage. LDMOS transistors.

Note 4:

The threshold voltage (V_{GSTH}) of LDMOS transistors varies with device temperature. External temperature compensation may be required. See Sirenza application notes AN-067 LDMOS Bias Temperature Compensation.

Note 5:

This module was designed to have it's leads hand soldered to an adjacent PCB. The maximum soldering iron tip temperature should not exceed 700° F, and the soldering iron tip should not be in direct contact with the lead for longer than 10 seconds. Refer to app note AN054 (www.sirenza.com) for further installation instructions.

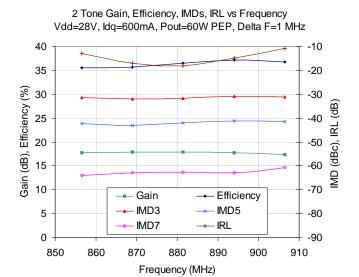


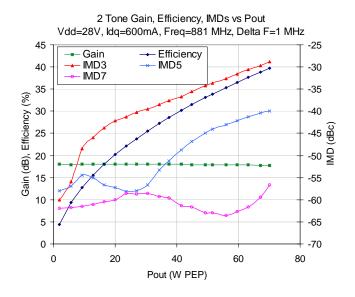
Caution: ESD Sensitive

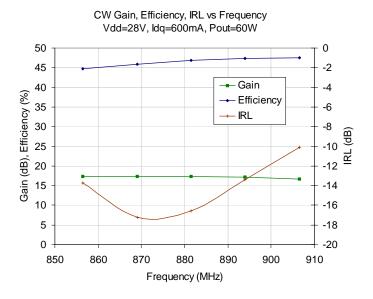
Appropriate precaution in handling, packaging and testing devices must be observed.

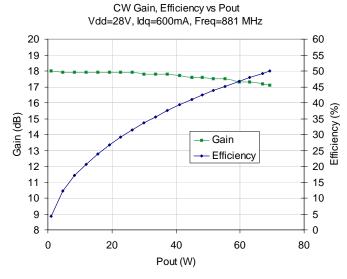


Typical Performance Curves



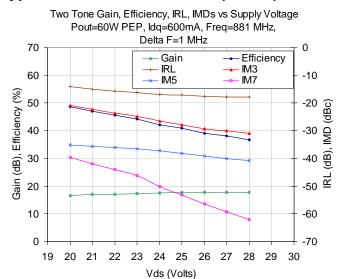


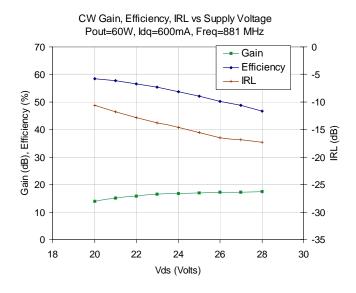


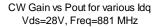


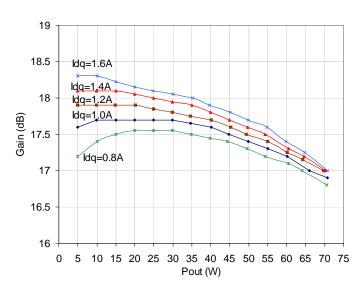


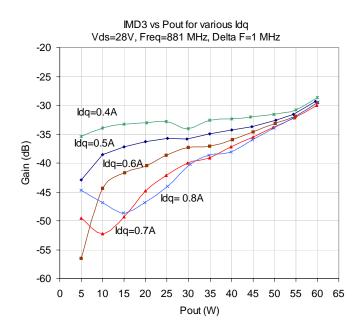
Typical Performance Curves (cont'd)









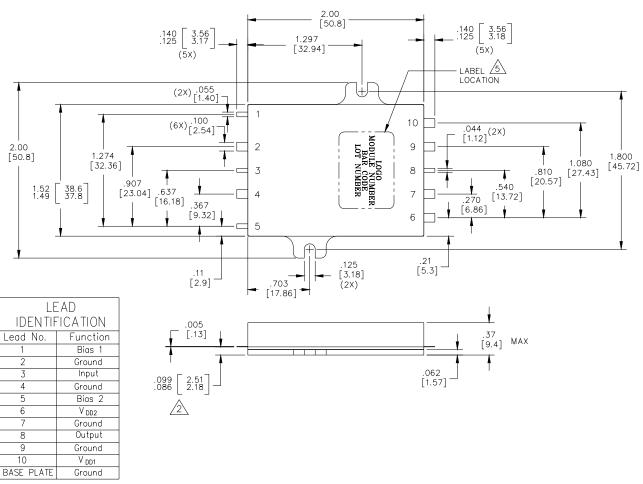


Note:

Evaluation test fixture information available on Sirenza Website, referred to as SDM-EVAL.



Package Outline Drawing



MODULE WEIGHT = 43gm NOMINAL

NOTES: UNLESS OTHERWISE SPECIFIED

1. INTERPRET DRAWING PER ANSI Y14.5..

2. MEASURE FROM THE BOTTOM OF THE LEADS.

3. DIMENSIONS ARE INCHES[MM].

4. LEAD IDENTIFICATION IS FOR REFERENCE ONLY.

ORIENTATION OF LABEL IS TO BE AS SHOWN.

Note:

Refer to Application note AN054, "Detailed Installation Instructions for Power Modules" for detailed mounting information.